

DATA SHEET

For a complete data sheet, please also download:

- The IC04 LOCMOS HE4000B Logic Family Specifications HEF, HEC
- The IC04 LOCMOS HE4000B Logic Package Outlines/Information HEF, HEC

HEF4012B **gates** Dual 4-input NAND gate

Product specification
File under Integrated Circuits, IC04

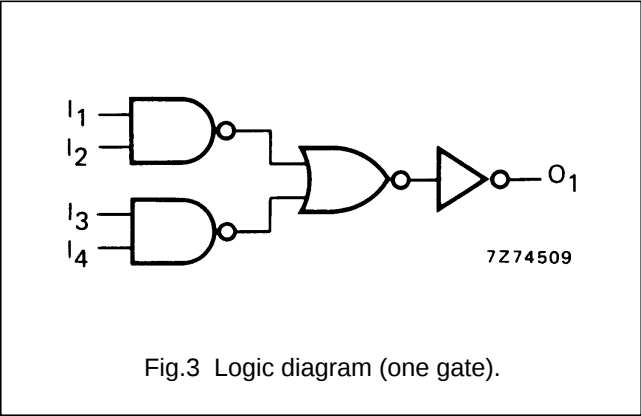
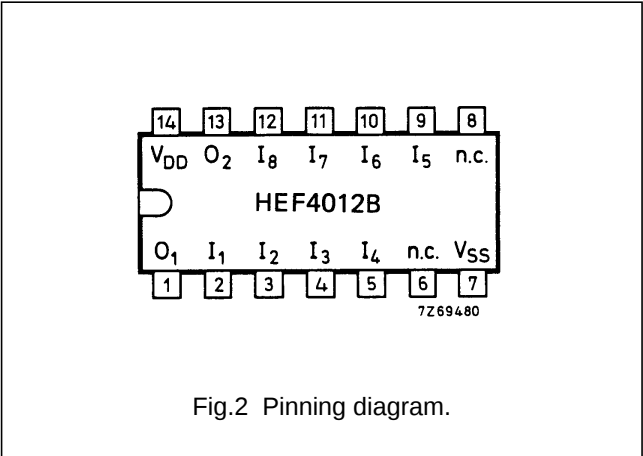
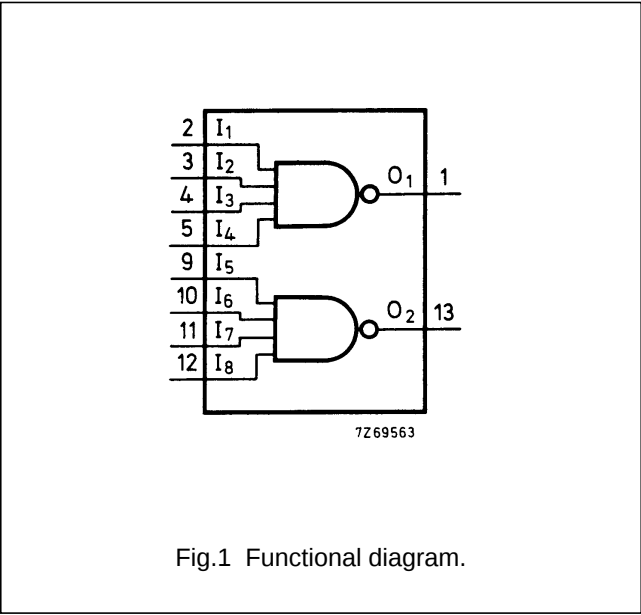
January 1995

Dual 4-input NAND gate

HEF4012B
gates

DESCRIPTION

The HEF4012B provides the positive dual 4-input NAND function. The outputs are fully buffered for highest noise immunity and pattern insensitivity of output impedance.



FAMILY DATA, I_{DD} LIMITS category GATES

see Family Specifications

- HEF4012BP(N): 14-lead DIL; plastic (SOT27-1)
- HEF4012BD(F): 14-lead DIL; ceramic (cerdip) (SOT73)
- HEF4012BT(D): 14-lead SO; plastic (SOT108-1)
- (): Package Designator North America

Dual 4-input NAND gate

HEF4012B
gates

AC CHARACTERISTICS

$V_{SS} = 0$ V; $T_{amb} = 25$ °C; $C_L = 50$ pF; input transition times ≤ 20 ns

	V_{DD} V	SYMBOL	TYP	MAX		TYPICAL EXTRAPOLATION FORMULA
Propagation delays $I_n \rightarrow O_n$ HIGH to LOW	5	t_{PHL}	70	135	ns	43 ns + (0,55 ns/pF) C_L
	10		25	50	ns	14 ns + (0,23 ns/pF) C_L
	15		20	35	ns	12 ns + (0,16 ns/pF) C_L
LOW to HIGH	5	t_{PLH}	70	140	ns	43 ns + (0,55 ns/pF) C_L
	10		30	60	ns	19 ns + (0,23 ns/pF) C_L
	15		25	50	ns	17 ns + (0,16 ns/pF) C_L
Output transition times HIGH to LOW	5	t_{THL}	60	120	ns	10 ns + (1,0 ns/pF) C_L
	10		30	60	ns	9 ns + (0,42 ns/pF) C_L
	15		20	40	ns	6 ns + (0,28 ns/pF) C_L
LOW to HIGH	5	t_{TLH}	60	120	ns	10 ns + (1,0 ns/pF) C_L
	10		30	60	ns	9 ns + (0,42 ns/pF) C_L
	15		20	40	ns	6 ns + (0,28 ns/pF) C_L

	V_{DD} V	TYPICAL FORMULA FOR P (μ W)	
Dynamic power dissipation per package (P)	5	$1100 f_i + \sum (f_o C_L) \times V_{DD}^2$	where f_i = input freq. (MHz) f_o = output freq. (MHz) C_L = load capacitance (pF) $\sum (f_o C_L)$ = sum of outputs V_{DD} = supply voltage (V)
	10	$4400 f_i + \sum (f_o C_L) \times V_{DD}^2$	
	15	$12\,900 f_i + \sum (f_o C_L) \times V_{DD}^2$	

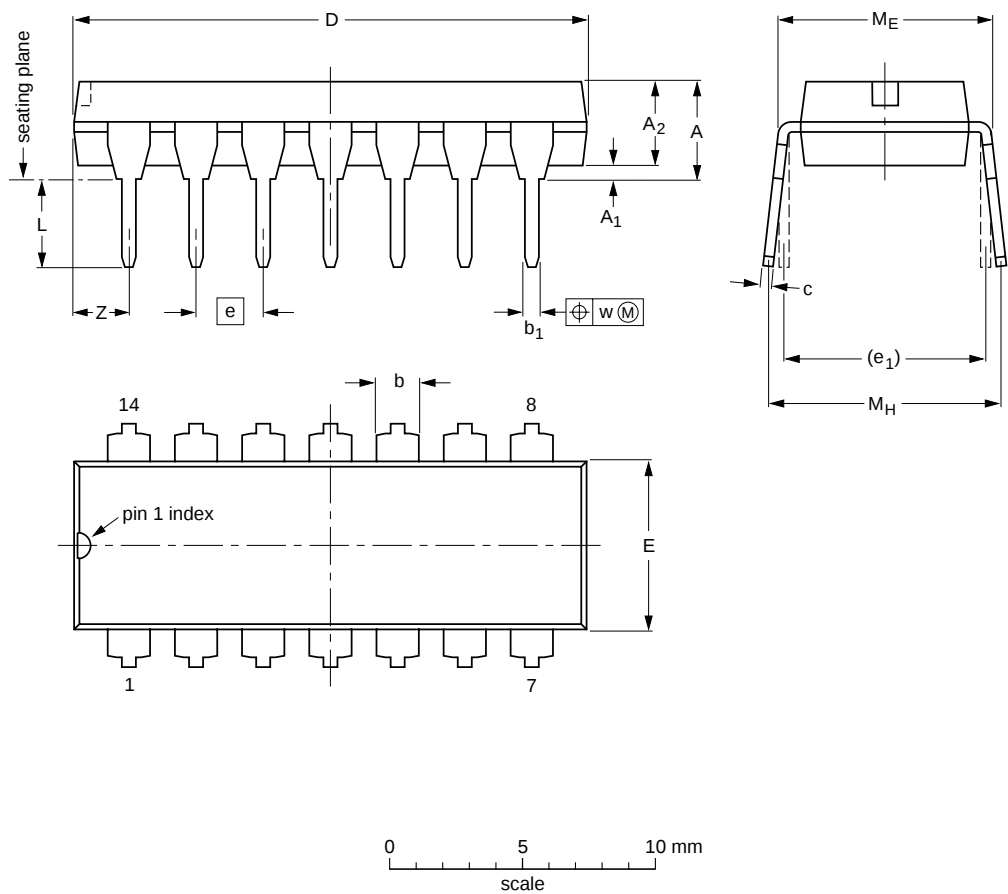
Package information

Package outlines

DIP

DIP14: plastic dual in-line package; 14 leads (300 mil)

SOT27-1

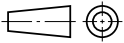


DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁ min.	A ₂ max.	b	b ₁	c	D ⁽¹⁾	E ⁽¹⁾	e	e ₁	L	M _E	M _H	w	Z ⁽¹⁾ max.
mm	4.2	0.51	3.2	1.73 1.13	0.53 0.38	0.36 0.23	19.50 18.55	6.48 6.20	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.2
inches	0.17	0.020	0.13	0.068 0.044	0.021 0.015	0.014 0.009	0.77 0.73	0.26 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.087

Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT27-1	050G04	MO-001AA				92-11-17 95-03-11

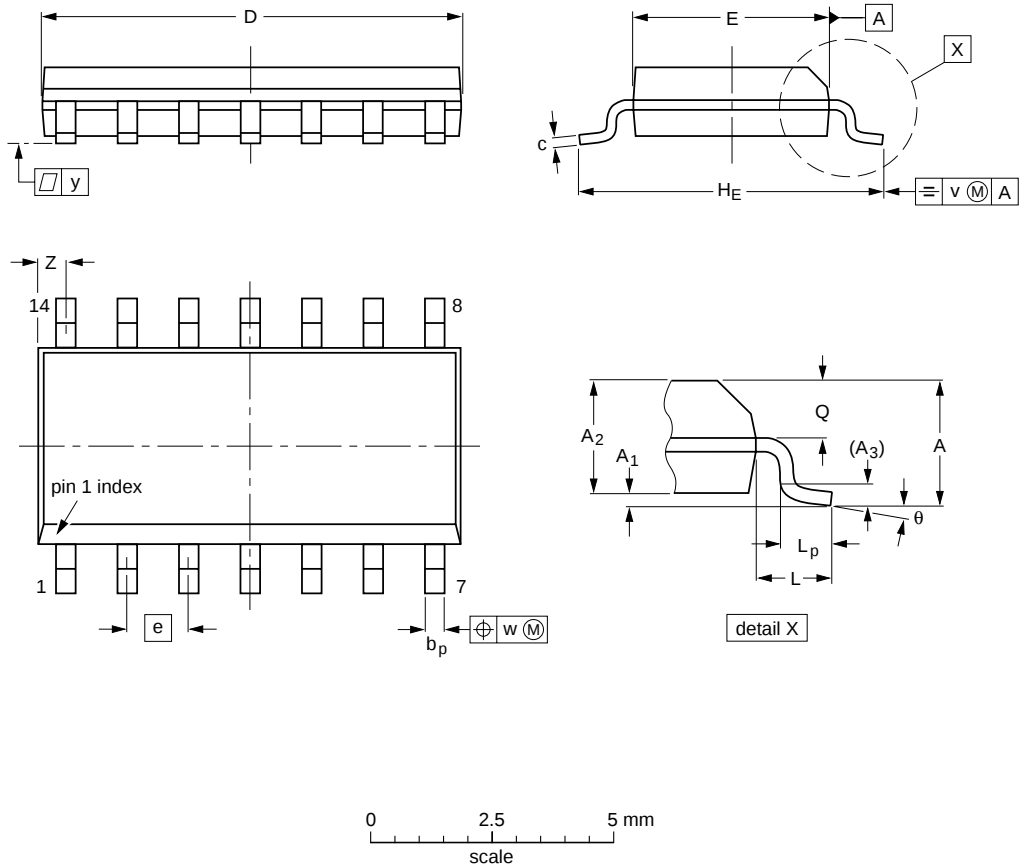
Package information

Package outlines

SO

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽¹⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	8.75 8.55	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8° 0°
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.35 0.34	0.16 0.15	0.050	0.244 0.228	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	

Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ			
SOT108-1	076E06S	MS-012AB				95-01-23 97-05-22